

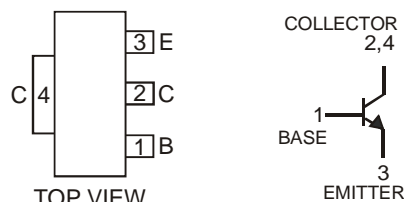
Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DCP53)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**



Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish - Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)



Schematic and Pin Configuration

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Units
Collector-Base Voltage	V_{CB0}	100	V
Collector-Emitter Voltage	V_{CEO}	80	V
Emitter-Base Voltage	V_{EBO}	5	V
Collector Current	I_C	1	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 3)	P_d	1	W
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to 150	$^\circ\text{C}$
Thermal Resistance, Junction to Ambient Air @ $T_A = 25^\circ\text{C}$ (Note 3)	$R_{\theta JA}$	125	$^\circ\text{C/W}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	100	—	—	V	$I_C = 100\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	80	—	—	V	$I_C = 10\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	5.0	—	—	V	$I_E = 10\mu\text{A}, I_C = 0$
Collector-Base Cutoff Current	I_{CBO}	—	—	0.1 20	μA	$V_{CB} = 30\text{V}, I_E = 0$ $V_{CB} = 30\text{V}, I_E = 0, T_A = 150^\circ\text{C}$
Emitter-Base Cutoff Current	I_{EBO}	—	—	10	μA	$V_{EB} = 5.0\text{V}, I_C = 0$
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h_{FE}	25	—	—	—	$I_C = 5.0\text{mA}, V_{CE} = 2.0\text{V}$ $I_C = 150\text{mA}, V_{CE} = 2.0\text{V}$ $I_C = 500\text{mA}, V_{CE} = 2.0\text{V}$
		40	—	250		
		25	—	—		
		100	160	250		
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	0.5	V	$I_C = 500\text{mA}, I_B = 50\text{mA}$
Base-Emitter Turn-On Voltage	$V_{BE(ON)}$	—	—	1.0	V	$I_C = 500\text{mA}, V_{CE} = 2.0\text{V}$
SMALL SIGNAL CHARACTERISTICS						
Current-Gain-Bandwidth Product	f_T	—	200	—	MHz	$I_C = 50\text{mA}, V_{CE} = 5.0\text{V}, f = 100\text{MHz}$

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 4. Pulse Test: Pulse width = $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

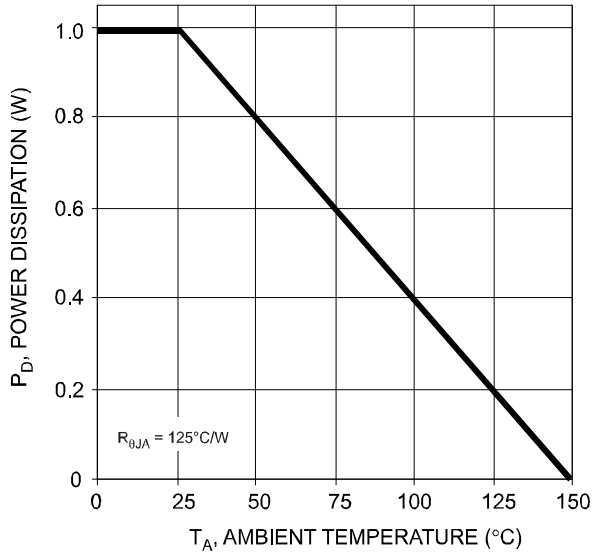


Fig. 1 Power Dissipation vs. Ambient Temperature

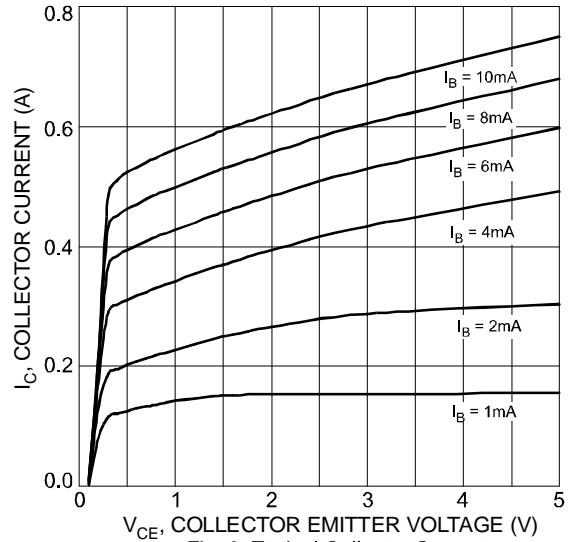


Fig. 2 Typical Collector Current vs. Collector Emitter Voltage

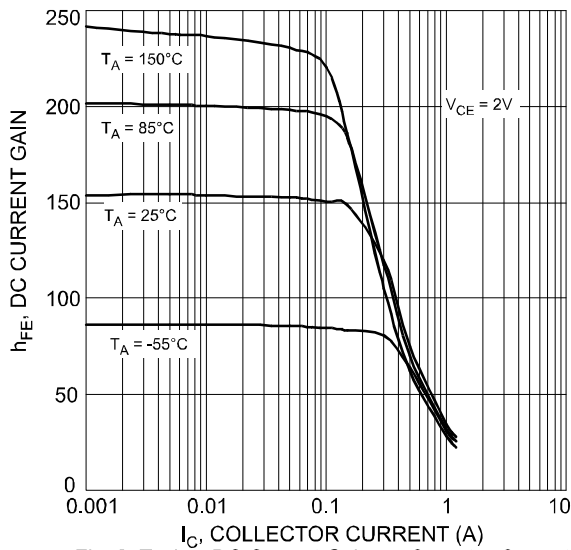


Fig. 3 Typical DC Current Gain vs. Collector Current

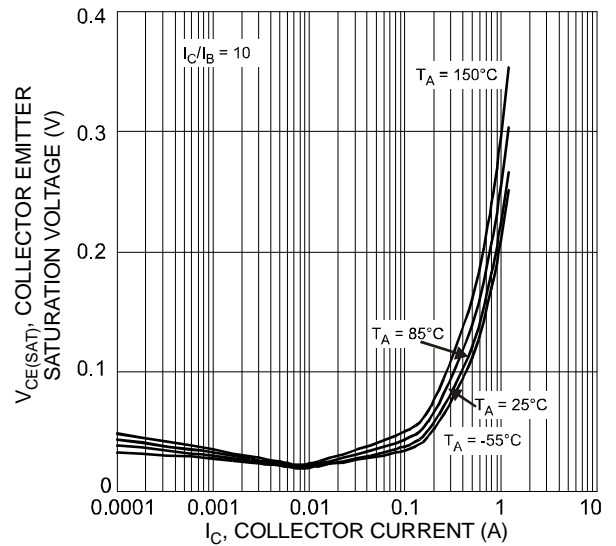


Fig. 4 Typical Collector Emitter Saturation Voltage vs. Collector Current

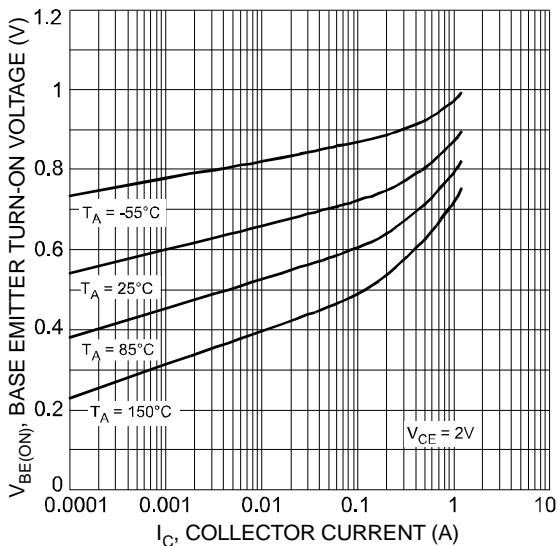


Fig. 5 Typical Base Emitter Turn-On Voltage vs. Collector Current

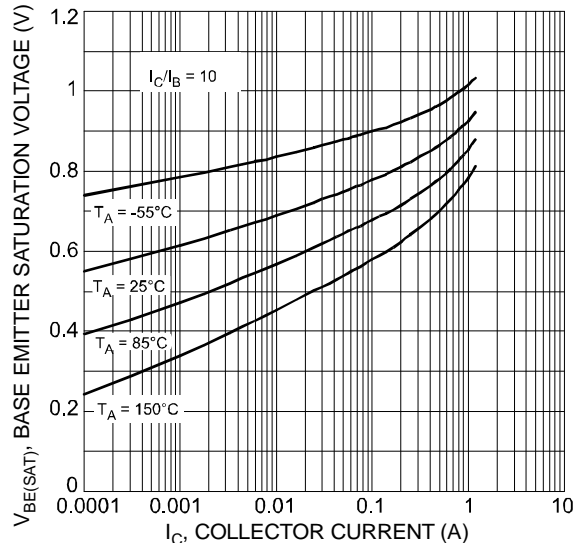


Fig. 6 Typical Base Emitter Saturation Voltage vs. Collector Current

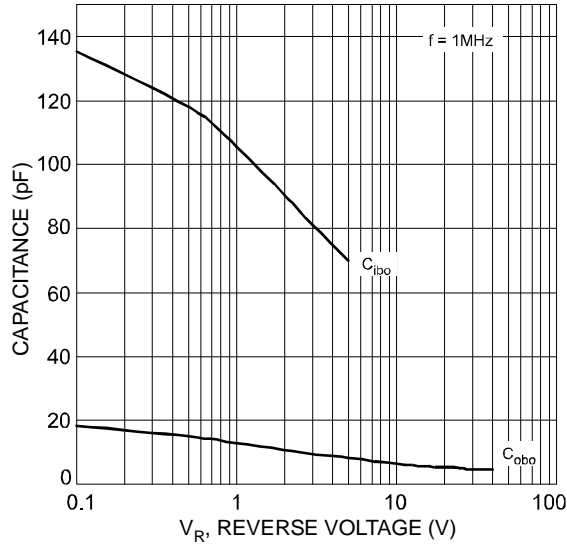


Fig. 7 Typical Capacitance Characteristics

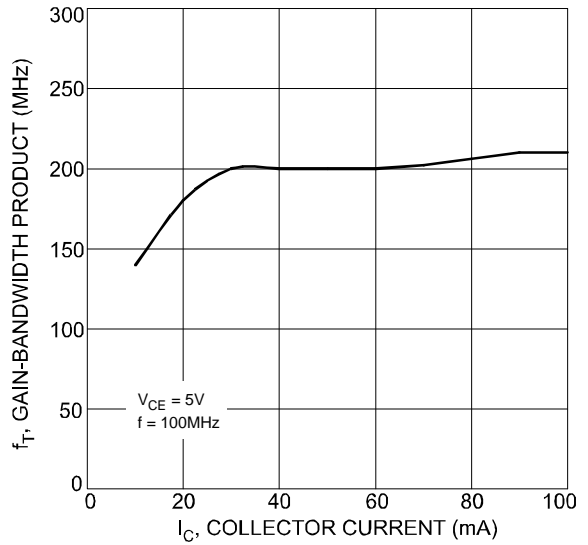


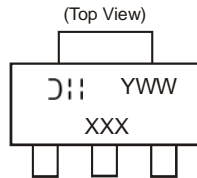
Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 5)

Device	Packaging	Shipping
DCP56-13	SOT-223	2500/Tape & Reel
DCP56-16-13	SOT-223	2500/Tape & Reel

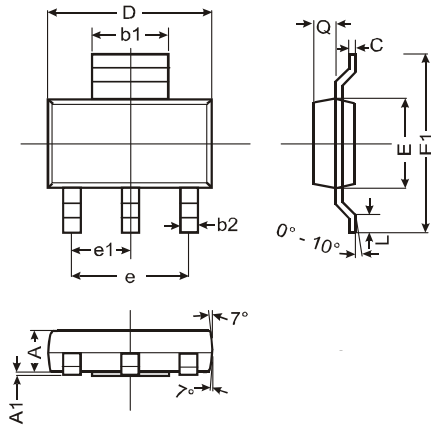
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



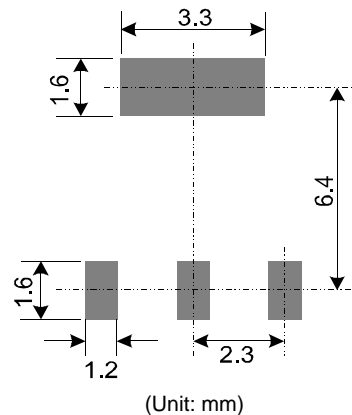
XXX = Product Type Marking Code ex. N18 = DCP56
N18-16 = DCP56-16
 $\text{D}||$ = Manufacturer's Marking Code
YWW = Date Code Marking
Y = Last Digit of Year ex: 7 = 2007
WW = Week Code 01-52

Package Outline Dimensions



SOT-223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89

All Dimensions in mm

Suggested Pad Layout: (Based on IPC-SM-782)**IMPORTANT NOTICE**

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